

Abstract

The present invention provides a resin composition for printed wiring board to be used for electronic devices in which operating frequency exceeds 1 GHz, and a varnish, a prepreg and a metal clad laminated board using the same. One invention of the present invention is a resin composition for printed wiring board containing a cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, an epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule, and a varnish, a prepreg and a metal clad laminated board using the same.